PRINTED WIRING BOARD AND ITS MANUFACTURE

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Abstract of **JP 2000244101 (A)**

PROBLEM TO BE SOLVED: To establish a reliable junction between an IC chip and a conductor circuit by forming a solder resist layer having a plurality of openings on a substrate and forming a solder bump in each opening and then flattening the tops of part of the solder bumps. SOLUTION: A conductor circuit 34 is formed on both sides of a core substrate 30 of a multilayer printed wiring board 10 and built-up interconnection layers 80A, 80B are formed on the conductor circuits 34. The built-up interconnection layer 80A comprises a via hole 60 and an interlayer resin insulating layer 50 formed with a conductor circuit, and the build-up interconnection layer 80B comprises a via hole 160 and an interlayer resin insulating layer 150 formed with a conductor circuit 158.; Then, a solder resist layer 70 is formed on the via hole 160 and on the conductor circuit 158, solder bumps 76U, 76D are formed through a plurality of openings 71 formed in the solder resist layers 70, and the tops of the solder bumps 76U are formed into flat faces 77.